

ABSTRACT

An ultrasonic bonding device includes a heater plate on which a lead frame having a plurality of leads is positioned in place. A semiconductor chip is mounted on the lead frame. A holding member presses the leads of the lead frame against the heater plate. A bonding tool applies ultrasonic energy to a position where a wire is in contact with an electrode of the semiconductor chip so that the wire is bonded to the electrode. The bonding tool also applies ultrasonic energy to a position where said wire is in contact with one of the leads so that the wire is bonded to the lead. A holding surface of the holding member for contact with the leads has a surface roughness higher than that of a supporting surface zone of the heater plate for contact with the leads.